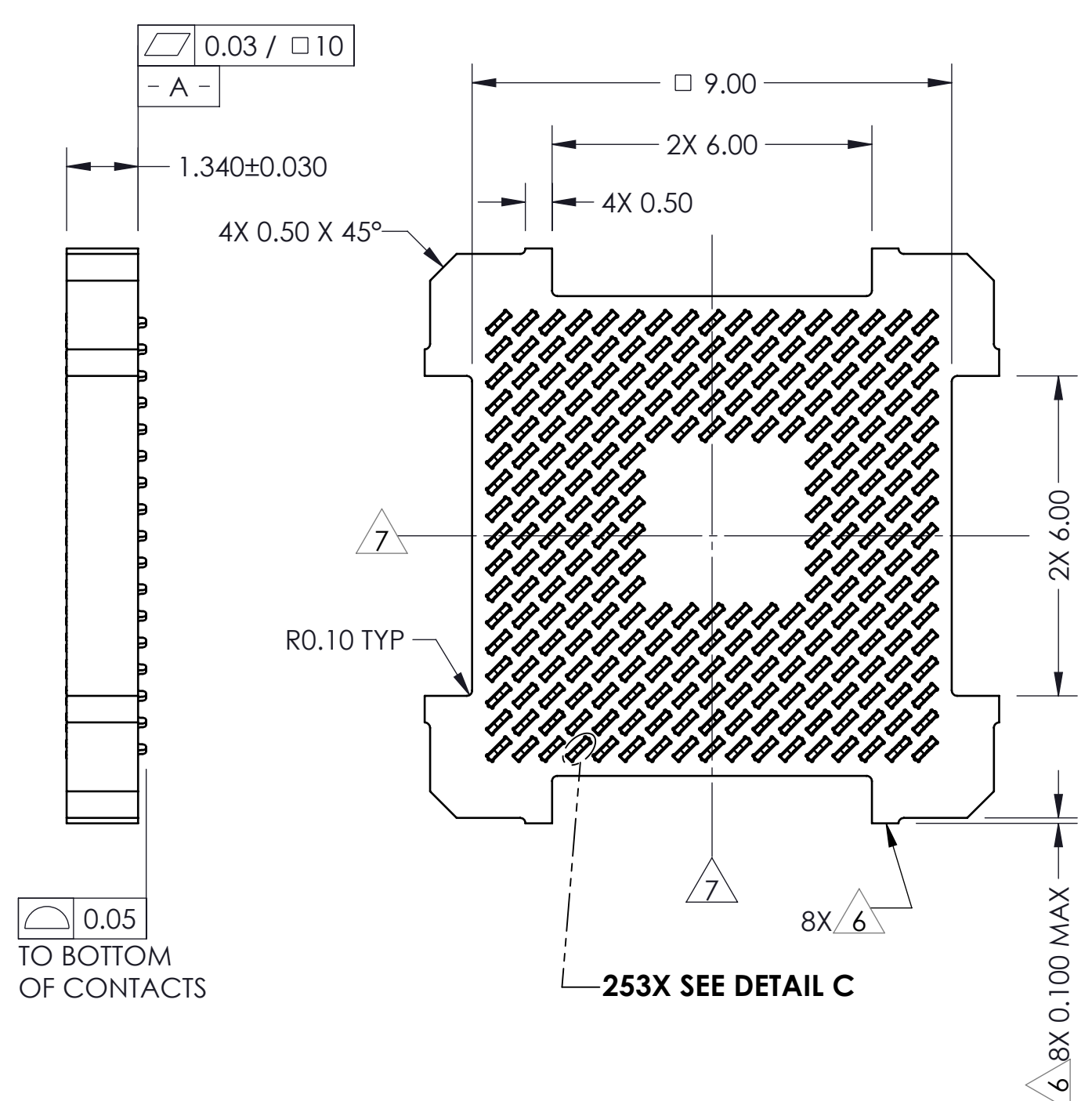
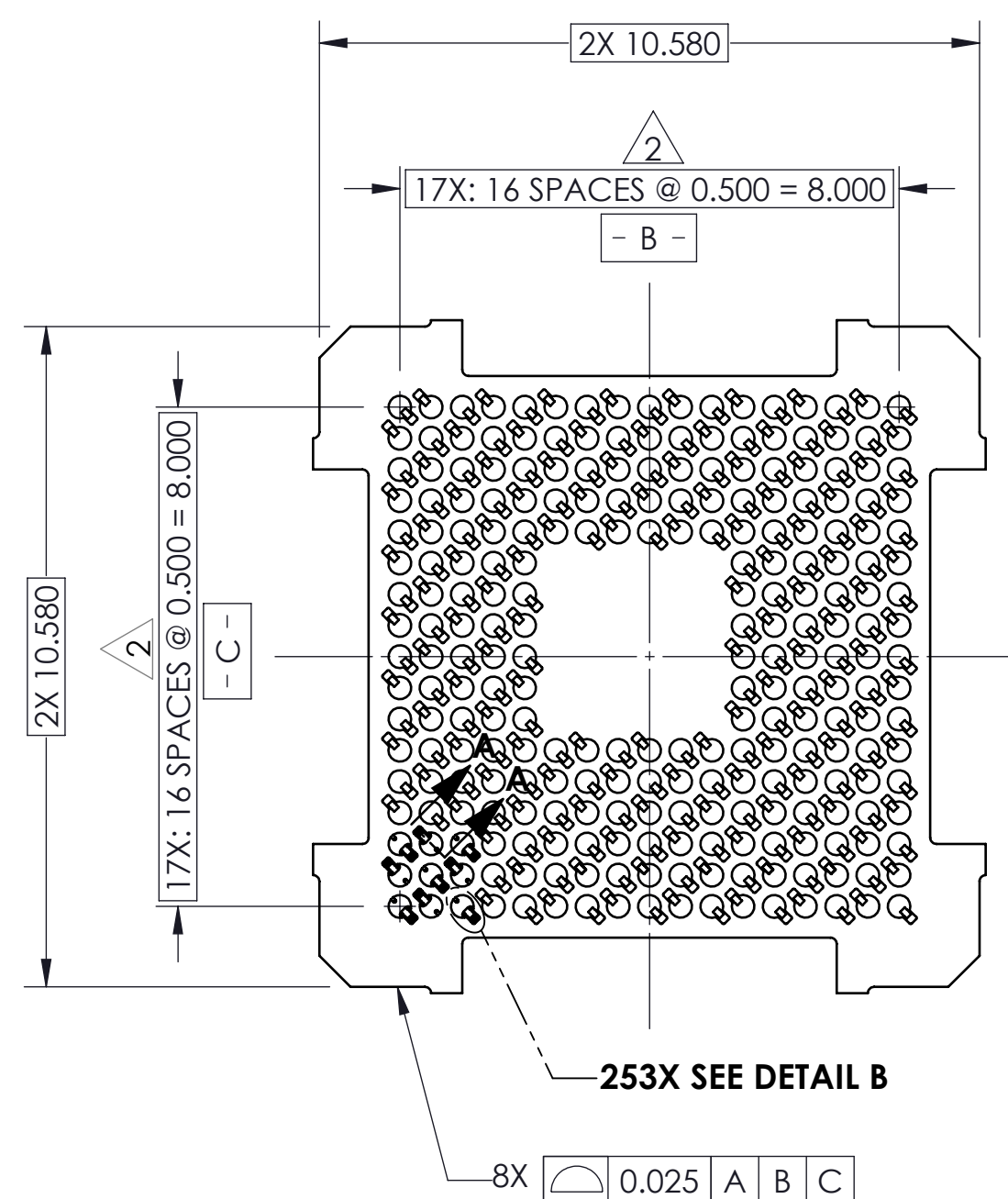
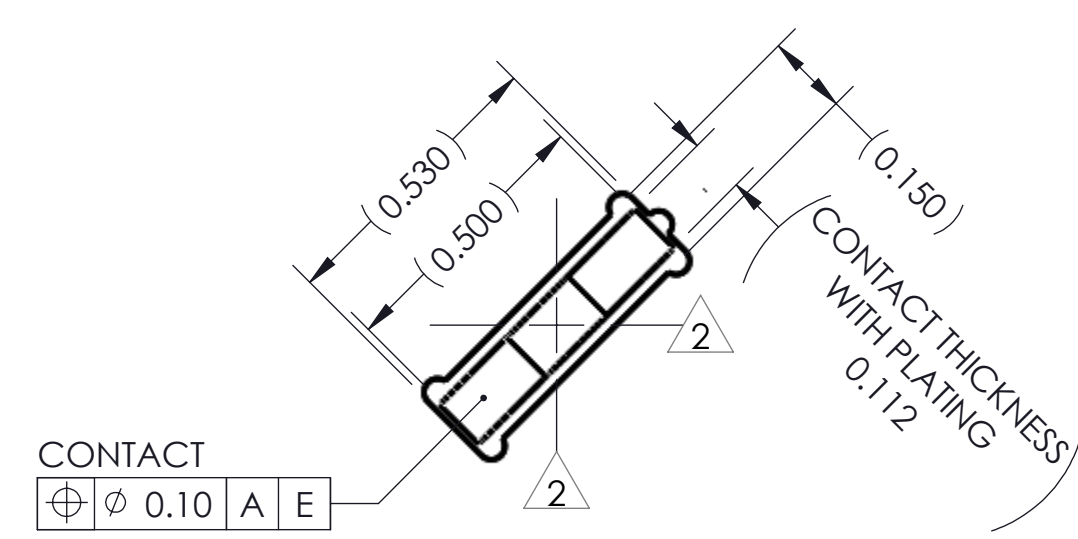
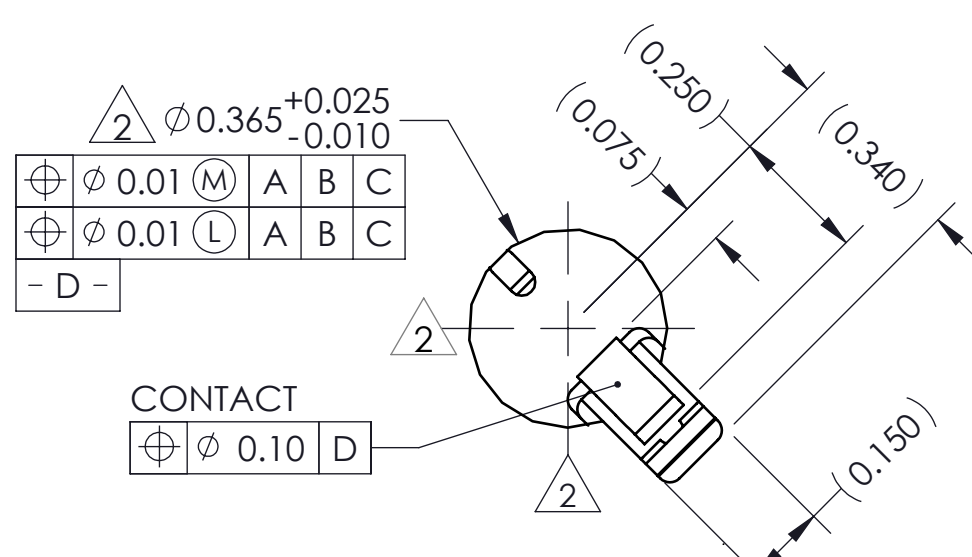
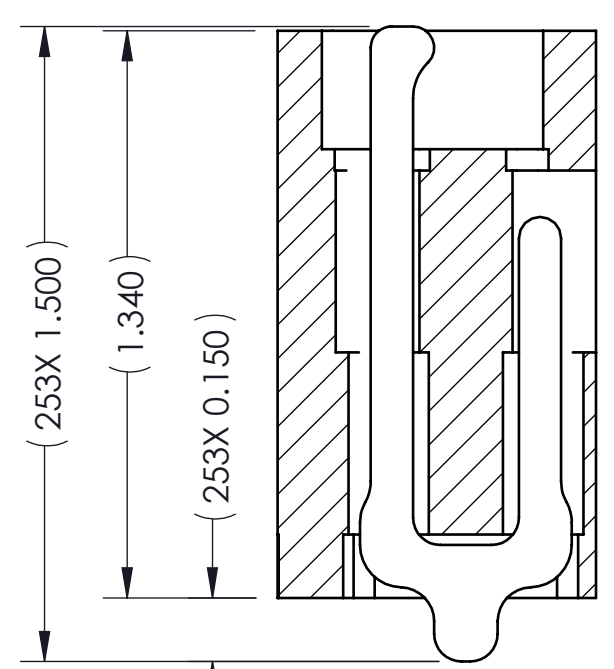


REV	ECO	BY	DESCRIPTION	APV	DATE
A	31414	PVW	Initial Design	MP	11/04/13
B	31664	RS	Stencil Flex part number was 104553-0312.	NSJ	06/25/15



- Notes:
- Reference HSI0 Technologies part number 103862-0001 for solder attachment.
  - Locates center of contact/ slot.
  - Reference HSI0 Technologies part number 103863-0001 for application notes.
  - Footprint part number is 104311-0398.
  - Datums **- B -** and **- C -** are determined by  $\phi 0.365$  openings in corner slots.
  - Tooling marks permitted. Maximum 0.100 protrusion (shown).
  - E -** Center of contact pattern.

Part Number	Description
107610-0011	SCKT, 253G4010.5-0.50
103864-0073	PRESS, DEVICE INSERT, GRYP 10.5X12.5 (SOLD SEPARATELY)
105900-0004	EXTRACTION TOOL, 4 X 53 (SOLD SEPARATELY)
104553-0313	STENCIL, FLEX, 253G4010.5-0.50 (SOLD SEPERATELY)
106083-0076	FRAME, ALIGN, G40, 10.5X12.5 (SOLD SEPARATELY)



**HSIO technologies**  
PROPRIETARY AND CONFIDENTIAL

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UNLESS OTHERWISE SPECIFIED:  
DIMENSIONS ARE IN MILLIMETERS  
TOLERANCES:  
ANGULAR:  $\pm 1^\circ$   
X.X  $\pm 0.25$   
X.XX  $\pm 0.10$   
X.XXX  $\pm 0.050$

INTERPRET GEOMETRIC TOLERANCING PER:  
MATERIAL: SEE BOM  
FINISH:  
DO NOT SCALE DRAWING

NAME	DATE
PVW	11/04/13
MP	11/04/13

LEGEND:  
 △ NOTE CALLOUT  
 ○ REVISION CHANGE  
 ○ ITEM NUMBER

**HSIO TECHNOLOGIES, LLC.**  
13300 67th AVENUE NORTH  
MAPLE GROVE, MINNESOTA 55311  
763-447-6260

TITLE:  
SCKT, 253G4010.5-0.50,  
W/O SOLDER BALLS

DWG. NO. **107610-0011** REV **B**

SCALE: 10:1 SIZE: C SHEET 1 OF 2

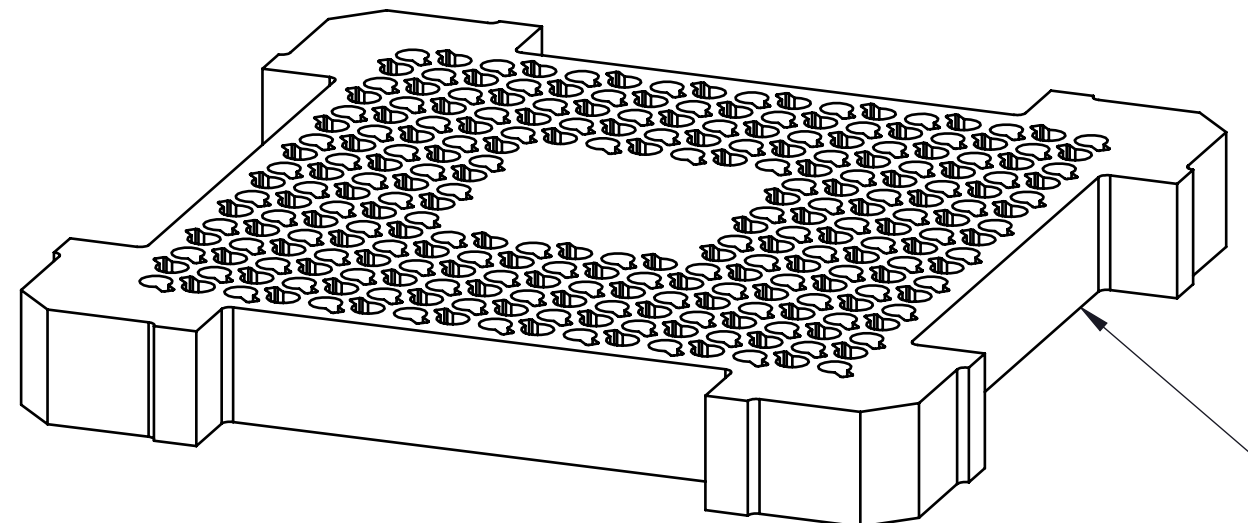
**SOCKET FOR DEVICES THAT ARE WITHIN THESE SPECIFICATIONS**

Lead Count	<b>N</b>	253	Package Size	<b>D</b>	10.50
Columns	<b>ND</b>	17		<b>E</b>	10.50
Rows	<b>NE</b>	17	Ball Spacing	<b>D1</b>	8.000
Pitch	<b>e</b>	0.500		<b>E1</b>	8.000
Ball Size	<b>b</b>	0.30±0.05	Encapsulant/ Top Size	<b>D2</b>	n/a
Total Thickness	<b>A</b>	n/a		<b>E2</b>	n/a
Ball Height	<b>A1</b>	0.225 MIN	Pattern Style	Irregular*	
Substrate Thickness	<b>A2</b>	n/a	Perimeter Rows	n/a	
Top Thickness	<b>A3</b>		Center Array	n/a	

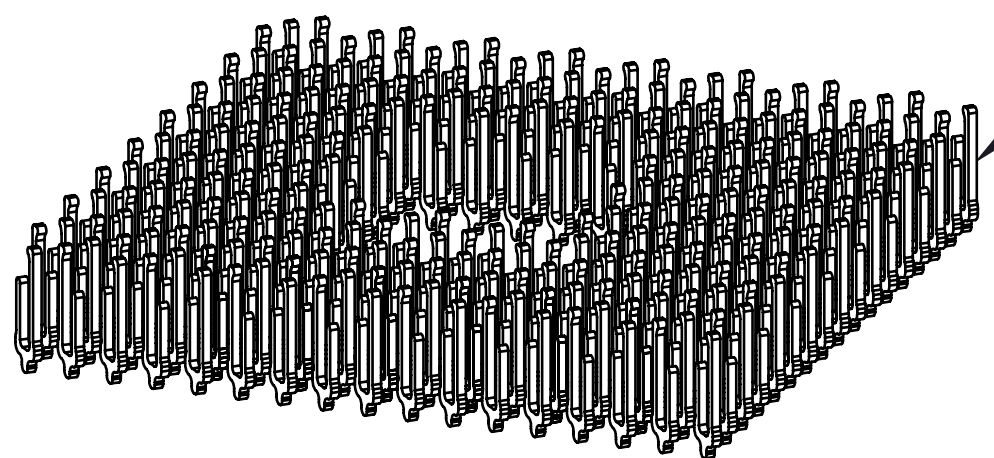
**Form Tolerances**

Edge	<b>aaa</b>	0.10	Bottom	<b>ddd</b>	0.08
Substrate	<b>bbb</b>	0.10	Position	<b>eee</b>	0.10
top	<b>ccc</b>	0.10	Position	<b>fff</b>	0.05

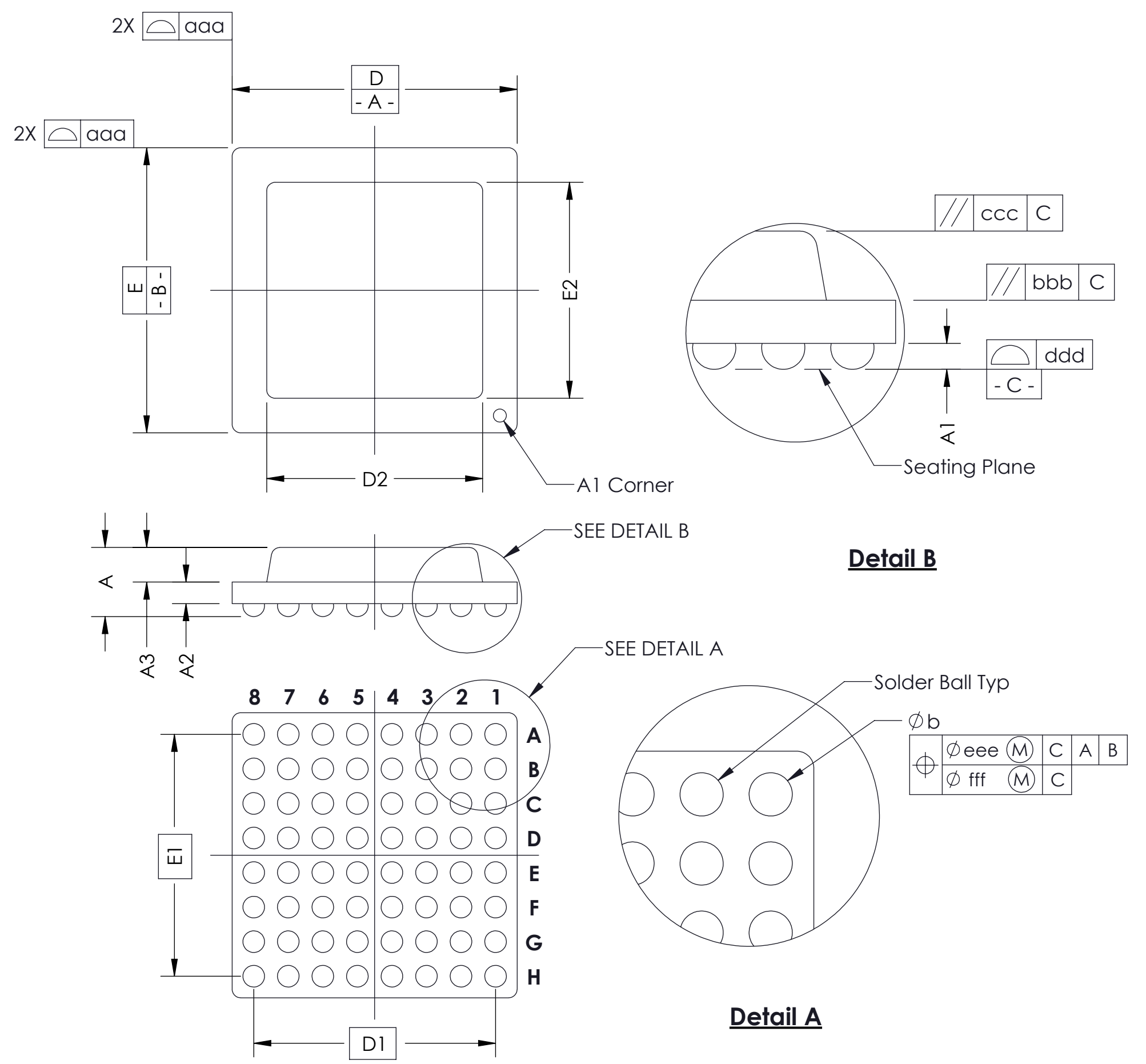
All dimensions are in millimeters.  
\* See footprint for pattern details.



HOUSING  
107613-0011



256X CONTACT  
104468-0015



**Generic Representation with Full Grid Array**

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UNLESS OTHERWISE SPECIFIED:	NAME	DATE	<b>HSIO TECHNOLOGIES, LLC.</b> 13300 67th AVENUE NORTH MAPLE GROVE, MINNESOTA 55311 763-447-6260	
DIMENSIONS ARE IN MILLIMETERS	DRAWN	PVW		11/04/13
TOLERANCES: ANGULAR: ± 1° X.X ±0.25 X.XX ±0.10 X.XXX ±0.050	CHECKED	MP		11/04/13

LEGEND:  
 △ NOTE CALLOUT  
 ◻ REVISION CHANGE  
 ○ ITEM NUMBER

**HSIO** technologies

TITLE:	DWG. NO.	REV
SCKT, 253G4010.5-0.50, W/O SOLDER BALLS	107610-0011	B
SCALE: 10:1	SIZE: C	SHEET 2 OF 2